

#### IEC QUALITY ASSESSMENT SYSTEM (IECQ)

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# Schedule of Scope to Certificate of Approval Independent Testing Laboratory

IECQ Certificate No.: IECQ-L ULTW 21.0003-03
CB Certificate No.: 50600528 ITL

Schedule Number: IECQ-L ULTW 21.0003-03-S Rev No.: 3 Revision Date: 2025/05/26 Page 1 of 2

## **Appendix-1 (50600528 ITL) Schedule of Scope to Certificate of Approval**

Test Technology 測試項目	Test Method 測試標準	
Temperature, Bias, And Operating Life 温度偏压寿命试验	JEDEC JESD22-A108; AEC Q100-005。 SHJF-WI-RA-004	
Steady-State Temperature-Humidity Bias Life Test (THB) 恒定温湿度偏压寿命	JEDEC JESD22-A101 SHJF-WI-RA-007	
Highly Accelerated Temperature and Humidity Stress Test (HAST) 高加速温湿度应力试验	JEDEC JESD22-A110 SHJF-WI-RA-001	
High Temperature Storage Life (HTSL) 高温存储寿命试验	JEDEC JESD22-A103 SHJF-WI-RA-008	
Temperature Cycling (TC) 温度循环试验	JEDEC JESD22-A104 SHJF-WI-RA-009	
Accelerated Moisture Resistance - Unbiased Autoclave (PCT) 高压蒸煮试验	JEDEC JESD22-A102 SHJF-WI-RA-002	
Low Temperature Storage Life (LTSL) 低温存储寿命试验	JEDEC JESD22-A119 SHJF-WI-RA-010	
Power and Temperature Cycling (PTC) 功率和温度循环	JEDEC JESD22-A105 SHJF-WI-RA-013	
Early Life Failure Rate (ELFR) 早天测试	AEC Q100-008; JEDEC JESD22-A108。 SHJF-WI-RA-012	

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Preconditioning of Nonhermetic Surface Mount Devices Prior to Reliability Testing (Pre-con) 非密封表面贴装器件可靠性测试前的预处理	JEDEC JESD22-A113; JEDEC J-STD-020。 SHJF-WI-RA-011
Accelerated Moisture Resistance-Unbiased HAST (UHAST) 无偏压高加速试验	JEDEC JESD22-A118 SHJF-WI-RA-003
Resistance to Solder Shock for Through-Hole Mounted Devices 通孔安装器件的耐焊接性	JESD22-B106 SHJF-WI-RA-015
Solderability Tests for Component Leads, Terminations, Lugs, Terminals And Wires 元件引线、端子、挂耳、电线可焊性测试	J-STD-002 SHJF-WI-RA-014
Acoustic Microscopy for Non-Hermetic Encapsulated Electronic Devices 非密封封装电子器件的声学显微镜	IPC/JEDEC J-STD-035 SHJF-WI-RA-107

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Technical Reviewer of DQS:		0

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